

BONDING METHOD, BONDING APPARATUS AND SEALING MEANS

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ABSTRACT OF THE DISCLOSURE

10       A silicon substrate in which MEMS devices are formed  
and a quartz substrate used to seal the silicon substrate  
are tentatively bonded to each other. While the silicon  
substrate and quartz substrate are being pressed using a  
pressure jig, light having a wavelength that is absorbed  
into the silicon substrate but not into the pressure jig  
and quartz substrate is radiated from light sources to  
15       the interface between the silicon substrate and quartz  
substrate. Thus, the interface is heated and the silicon  
substrate and quartz substrate are bonded.